2824

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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| Applicant: | Rincon et al |
| Appl. No.: | 09/992,065 |
| Filed: | November 21, 2001 |
| Title: | Dual Plane Probe Card ... |
| Art Unit: | 2829 |
| Examiner: | Nguyen |
| Docket: | TI-32568 |

7/a D. Scott 2-19-03

Assistant Commissioner
for Patents
Box NonFee Amendment
Washington, DC 20231

**MAILING CERTIFICATE**
I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231 today.

Gracia Sansom 2-6-03
Gracia Sansom Date

AMENDMENT

Dear Sir:

In response to the Office Action mailed 11/06/2002, please amend as shown on the attached sheets: "Version with markings to show changes made" and "Clean copy".

REMARKS

Claims 1-16 are pending in the application with claims 1-12 rejected and claims 13-16 withdrawn from consideration. Reexamination and reconsideration are hereby requested.

Claims 1-12 were rejected as anticipated by Kasukabe. The Examiner cited Kasukabe Fig.2.

Applicants reply that amended claim 1 clarifies that the sloped intermediate area is linear (not curved). Kasukabe has a flexible multilayer film 44 which is pressed into position and necessarily is curved between the support by circuit board 50 and the pressing member 43; this has no suggestion of a linear sloped intermediate area.

Respectfully submitted,

Carlton H. Hoel
Reg. No. 29,934
Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, Texas 75265
972.917.4365

1.(amended) A dual plane probe card apparatus for contacting and testing integrated circuit chips including:

-a probe card substrate having first and second major surfaces;

-said probe card substrate offset to form a centrally located horizontal plane, a linear sloped intermediate area, and a peripheral plane parallel to the first horizontal plane;

-a plurality of probe contacts arrayed on the first surface of said central plane in a pattern to mirror the contact pads of a DUT;

-an array of conductive traces adhered to said first substrate surface by a flexible insulating film wherein the traces fan from the probe contacts to conductive vias on the peripheral plane; and

-an array of conductive vias connecting said conductive traces adhered to the first surface to probe head contacts on the second surface.

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-a plurality of probe contacts arrayed on the first surface of said central plane in a pattern to mirror the contact pads of a DUT;

-an array of conductive traces adhered to said first substrate surface by a flexible insulating film wherein the traces fan from the probe contacts to conductive vias on the peripheral plane; and

-an array of conductive vias connecting said conductive traces adhered to the first surface to probe head contacts on the second surface.